

provided on said substrate from a region in which said semiconductor chip is mounted to said protective layer, wherein portions of the interconnect pattern connected to the electrodes of the semiconductor chip remain substantially flat.

50. (Amended) A method of manufacturing a semiconductor chip, comprising:

providing an adhesive over a substrate which includes an interconnect pattern formed thereover and a protective layer covering said interconnect pattern, said substrate having a first region on which a semiconductor chip is mounted and a second region which surrounds said first region, said protective layer having an edge portion on said interconnect pattern in said second region, said edge portion, said first region and a part of said interconnect pattern below said edge portion covered with said adhesive; and

providing said semiconductor chip including electrodes onto said first region to electrically connect said electrodes to said interconnect pattern, wherein portions of the interconnect pattern connected to the electrodes of the semiconductor chip remain substantially flat.

68. (Amended) A semiconductor device, comprising:

a substrate, said substrate having an interconnect pattern formed thereover, said substrate having a protective layer covering at least a part of said interconnect pattern;

a semiconductor chip, said semiconductor chip having electrodes, said electrodes electrically connected to said interconnect pattern, said semiconductor chip mounted on said substrate such that an edge of said semiconductor chip does not overlap with said protective layer; and

an adhesive, said adhesive adhering said semiconductor chip to said substrate, said adhesive provided on said substrate from a region in which said semiconductor chip is mounted to said protective layer, wherein portions of the interconnect pattern connected to the electrodes of the semiconductor chip remain substantially flat.